# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2985742

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
PRAMOD VASANT ARGADE	07/31/2014
ANDREW EVAN GRUBER	08/13/2014
CHIENTE HO	08/06/2014
STEWART GRIFFIN HALL	08/07/2014
LIN CHEN	08/01/2014

### **RECEIVING PARTY DATA**

Name:	QUALCOMM INCORPORATED	
Street Address: 5775 MOREHOUSE DRIVE		
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number		
Application Number:	14461890		

## **CORRESPONDENCE DATA**

**Fax Number:** (651)735-1102

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 651 735 1100

Email: pairdocketing@ssiplaw.com

Correspondent Name: SHUMAKER & SIEFFERT, P. A.

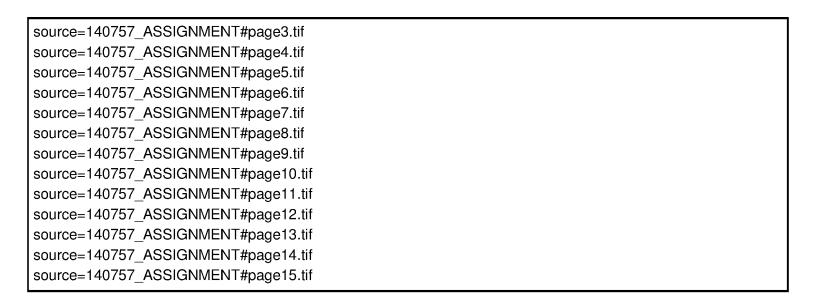
Address Line 1: 1625 RADIO DRIVE, SUITE 300

Address Line 4: WOODBURY, MINNESOTA 55125

ATTORNEY DOCKET NUMBER:	1212-775US01
NAME OF SUBMITTER:	SUSAN J. DALY
SIGNATURE:	/Susan J. Daly/
DATE SIGNED:	08/18/2014

**Total Attachments: 15** 

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## WHEREAS, WE,

- 1. Pramod Vasant Argade, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA,
- Andrew Evan Gruber, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Arlington, MA,
- 3. Chiente Ho, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Santa Clara, CA,
- 4. Stewart Griffin Hall, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA,
- 5. Lin Chen, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to EMULATION OF FUSED MULTIPLY-ADD OPERATIONS (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 14/461,890 filed August 18, 2014

Qualcomm Reference No. 140757, and all provisional applications relating thereto (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

QUALCOMM Ref. No. 140757 Page 3 of 3

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at≤	LOCATION CON.	7/31/14	Pramod V. Alegade  Pramod Vasant Argade
	LOCATION U	DATE	Pramod Vasant Argade
Done at	LOCATION , on		
	LOCATION	DATE	Andrew Evan Gruber
Done at _	LOCATION , on		
	LOCATION	DATE	Chiente Ho
Done at _	, on		
	LOCATION	DATE	Stewart Griffin Hall
Done at $\_$	on .		
	LOCATION	DATE	Lin Chen

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at		, on	
	LOCATION	DATE	Pramod Vasant Argade
Done at _	Boxboo, MA	on Avg 13, 2014	Andrew Evan Gruber
	LOCATION	ØATE '	Andrew Evan Gruber
Done at		_, on	
	LOCATION	DATE	Chiente Ho
Done at _	LOCATION	on	Stewart Griffin Hall
	LOCATION	DALL	Siewait Offilm Han
Done at _		, on	
	LOCATION	DATE	Lin Chen

PATENT QUALCOMM Ref. No. 140757 Page 1 of 3

## ASSIGNMENT

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PATENT QUALCOMM Ref. No. 140757 Page 2 of 3

applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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PATENT QUALCOMM Ref. No. 140757 Page 3 of 3

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Done at	, 011		
LOCATI		DATE	Framod Vasant Argade
Done at	, on		
LOCATI		DATE	Andrew Evan Gruber
Done at San Diego,	CA 08/0	06/2014	0,92,02
LOCATI	ON	DATE	Chiente Ho
Done at	, on		
LOCATI	ON	DATE	Stewart Griffin Hall
Done at	, on		
LOCATI	ON	DATE	Lin Chen

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Done at		, on		
	LOCATION		DATE	Pramod Vasant Argade
Done at		, on _		
	LOCATION		DATE	Andrew Evan Gruber
Done at		,on_		
	LOCATION		DATE	Chiente Ho
Done at	San Dego	, on	8/7/2019	Start Ergen Del
	LOCATION		DATE	Stewart Griffin Hall
Done at		, on		
	LOCATION		BATE	Lin Chen

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Done at	, on		
	LOCATION	DATE	Chiente Ho
Done at	, on		
	LOCATION	DATE	Stewart Griffin Hall
Done at	Scient Disple adifernia, on	8/3/14	
· · · · · · · · · · · · · · · · · · ·	LOCATION	DATE	Lin Chen

PATENT REEL: 033555 FRAME: 0167

**RECORDED: 08/18/2014**